

# SN55LBC173 QUADRUPLE LOW-POWER DIFFERENTIAL RECEIVER

SGLS081A – MARCH 1995 – REVISED JUNE 2000

- Meets EIA Standards RS-422-A, RS-423-A, RS-485, and CCITT V.11
- Designed to Operate With Pulse Durations as Short as 20 ns
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- Input Sensitivity . . .  $\pm 200$  mV
- Low-Power Consumption . . . 20 mA Max
- Open-Circuit Fail-Safe Design
- Pin Compatible With SN75173 and AM26LS32

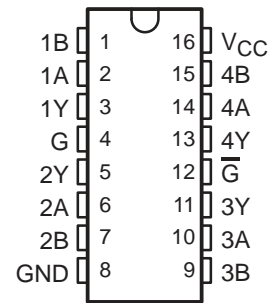
## description

The SN55LBC173 is a monolithic quadruple differential line receiver with 3-state outputs designed to meet the requirements of the EIA standards RS-422-A, RS-423-A, RS-485, and CCITT V.11. This device is optimized for balanced multipoint bus transmission at data rates up to and exceeding 10 million bits per second. The four receivers share two ORed enable inputs, one active when high, the other active when low. Each receiver features high input impedance, input hysteresis for increased noise immunity, and input sensitivity of  $\pm 200$  mV over a common-mode input voltage range of 12 V to  $-7$  V. Fail-safe design ensures that if the inputs are open circuited, the output is always high. The SN55LBC173 is designed using the Texas Instruments proprietary LinBiCMOS™ technology that provides low power consumption, high switching speeds, and robustness.

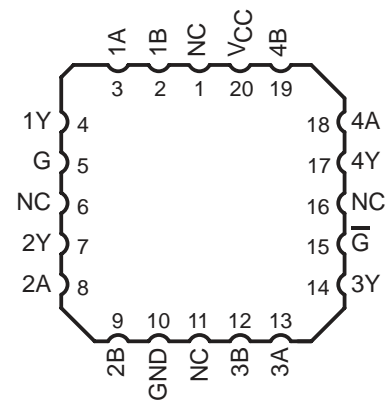
This device offers optimum performance when used with the SN55LBC172M quadruple line driver. The SN55LBC173 is available in the 16-pin CDIP (J), the 16-pin CPAK (W), or the 20-pin LCCC (FK) packages.

The SN55LBC173 is characterized over the military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

J OR W PACKAGE  
(TOP VIEW)



FK PACKAGE  
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinBiCMOS is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2000, Texas Instruments Incorporated

# SN55LBC173 QUADRUPLE LOW-POWER DIFFERENTIAL RECEIVER

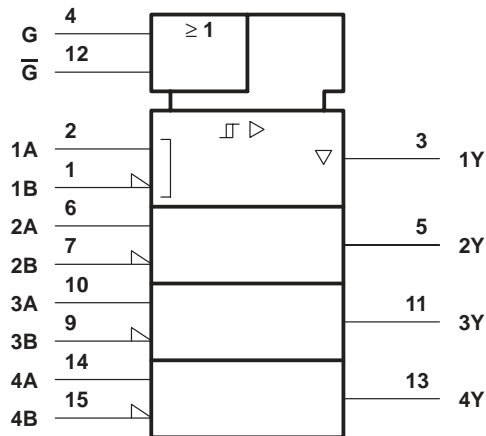
SGLS081A – MARCH 1995 – REVISED JUNE 2000

FUNCTION TABLE  
(each receiver)

DIFFERENTIAL INPUTS A-B	ENABLES		OUTPUT Y
	G	$\overline{G}$	
$V_{ID} \geq 0.2 V$	H X	X L	H H
$-0.2 V < V_{ID} < 0.2 V$	H X	X L	? ?
$V_{ID} \leq -0.2 V$	H X	X L	L L
X	L	H	Z
Open circuit	H X	X L	H H

H = high level, L = low level, X = irrelevant,  
Z = high impedance (off), ? = indeterminate

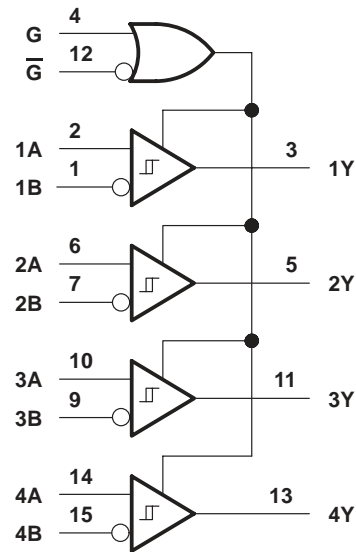
## logic symbol†



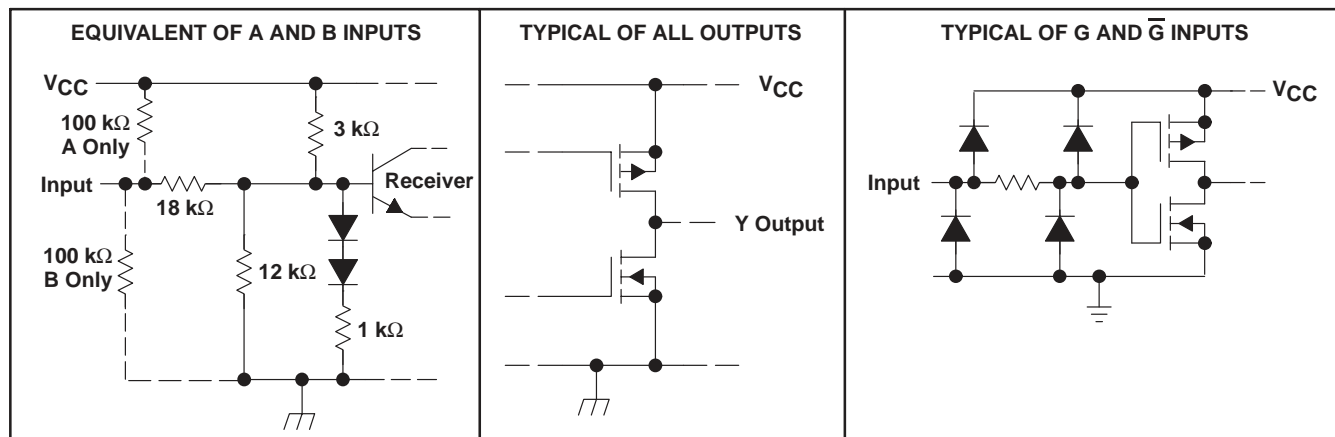
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the J or W package.

## logic diagram (positive logic)



**schematics of inputs and outputs**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ (see Note 1)	–0.3 V to 7 V
Input voltage, $V_I$ (A or B inputs)	$\pm 25$ V
Differential input voltage, $V_{ID}$ (see Note 2)	$\pm 25$ V
Data and control voltage range	–0.3 V to 7 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, $T_A$	–55°C to 125°C
Storage temperature range, $T_{stg}$	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.  
2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

**DISSIPATION RATING TABLE**

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 125^\circ\text{C}$ POWER RATING
FK	1375 mW	11.0 mW/°C	275 mW
J	1375 mW	11.0 mW/°C	275 mW
W	1000 mW	8.0 mW/°C	200 mW

**recommended operating conditions**

	MIN	NOM	MAX	UNIT
Supply voltage, $V_{CC}$	4.75	5	5.25	V
Common-mode input voltage, $V_{IC}$	–7		12	V
Differential input voltage, $V_{ID}$			$\pm 6$	V
High-level input voltage, $V_{IH}$	2			V
Low-level input voltage, $V_{IL}$				0.8
High-level output current, $I_{OH}$			–8	mA
Low-level output current, $I_{OL}$			16	mA
Operating free-air temperature, $T_A$	–55		125	°C

# SN55LBC173

## QUADRUPLE LOW-POWER DIFFERENTIAL RECEIVER

SGLS081A – MARCH 1995 – REVISED JUNE 2000

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
$V_{IT+}$	Positive-going input threshold voltage	$I_O = -8$ mA			0.2	V	
$V_{IT-}$	Negative-going input threshold voltage	$I_O = 8$ mA	-0.2			V	
$V_{hys}$	Hysteresis voltage ( $V_{IT+} - V_{IT-}$ )			45		mV	
$V_{IK}$	Enable input clamp voltage	$I_I = -18$ mA		-0.9	-1.5	V	
$V_{OH}$	High-level output voltage	$V_{ID} = 200$ mV, $I_{OH} = -8$ mA	3.5	4.5		V	
$V_{OL}$	Low-level output voltage	$V_{ID} = -200$ mV, $I_{OL} = 8$ mA		0.3	0.5	V	
		$V_{ID} = -200$ mV, $I_{OL} = 8$ mA, $T_A = 125^\circ\text{C}$			0.7		
$I_{OZ}$	High-impedance-state output current	$V_O = 0$ V to $V_{CC}$			$\pm 20$	$\mu\text{A}$	
$I_I$	Bus input current	A or B inputs	$V_{IH} = 12$ V, $V_{CC} = 5$ V, Other inputs at 0 V		0.7	1	mA
			$V_{IH} = 12$ V, $V_{CC} = 0$ V, Other inputs at 0 V		0.8	1	
			$V_{IH} = -7$ V, $V_{CC} = 5$ V, Other inputs at 0 V		-0.5	-0.8	
			$V_{IH} = -7$ V, $V_{CC} = 0$ V, Other inputs at 0 V		-0.4	-0.8	
$I_{IH}$	High-level input current	$V_{IH} = 5$ V			$\pm 20$	$\mu\text{A}$	
$I_{IL}$	Low-level input current	$V_{IL} = 0$ V			-20	$\mu\text{A}$	
$I_{OS}$	Short-circuit output current	$V_O = 0$		-80	-120	mA	
$I_{CC}$	Supply current	Outputs enabled, $I_O = 0$ , $V_{ID} = 5$ V		11	20	mA	
		Outputs disabled		0.9	1.4		

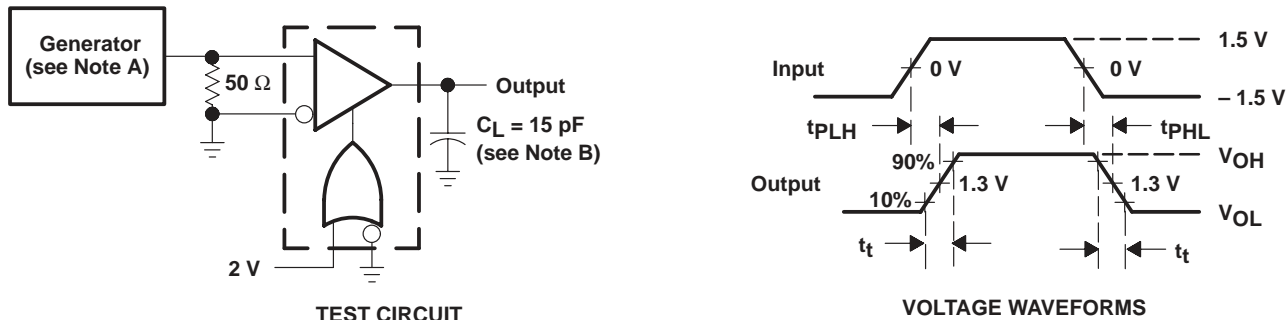
† All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^\circ\text{C}$ .

### switching characteristics, $V_{CC} = 5$ V, $C_L = 15$ pF

PARAMETER		TEST CONDITIONS	$T_A$	MIN	TYP	MAX	UNIT
$t_{PHL}$	Propagation delay time, high-to-low-level output	$V_{ID} = -1.5$ V to 1.5 V, See Figure 1	25°C	11	22	30	ns
			-55°C to 125°C	11		35	
$t_{PLH}$	Propagation delay time, low-to-high-level output	$V_{ID} = -1.5$ V to 1.5 V, See Figure 1	25°C	11	22	35	ns
			-55°C to 125°C	11		35	
$t_{PZH}$	Output enable time to high level	See Figure 2	25°C		17	40	ns
			-55°C to 125°C			45	
$t_{PZL}$	Output enable time to low level	See Figure 3	25°C		18	30	ns
			-55°C to 125°C			35	
$t_{PHZ}$	Output disable time from high level	See Figure 2	25°C		30	40	ns
			-55°C to 125°C			55	
$t_{PLZ}$	Output disable time from low level	See Figure 3	25°C		25	40	ns
			-55°C to 125°C			45	
$t_{sk(p)}$	Pulse skew ( $t_{PHL} - t_{PLH}$ )	See Figure 1	25°C		0.5	6	ns
			-55°C to 125°C			7	
$t_t$	Transition time	See Figure 1	25°C		5	10	ns
			-55°C to 125°C			16	

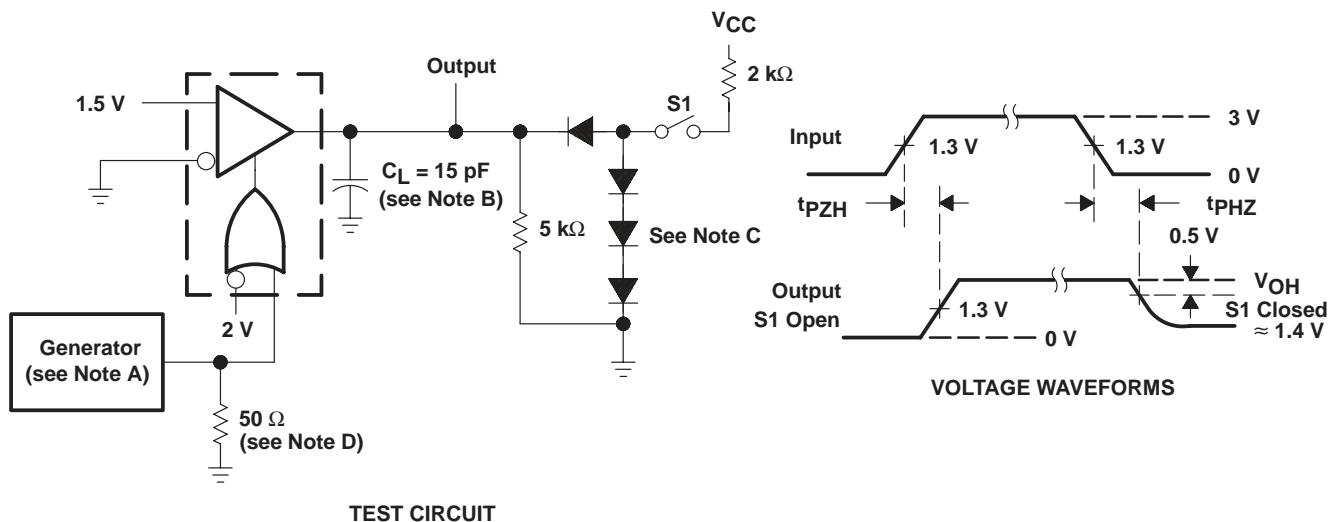


PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle  $\leq$  50%,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 1.  $t_{pd}$  and  $t_f$  Test Circuit and Voltage Waveforms



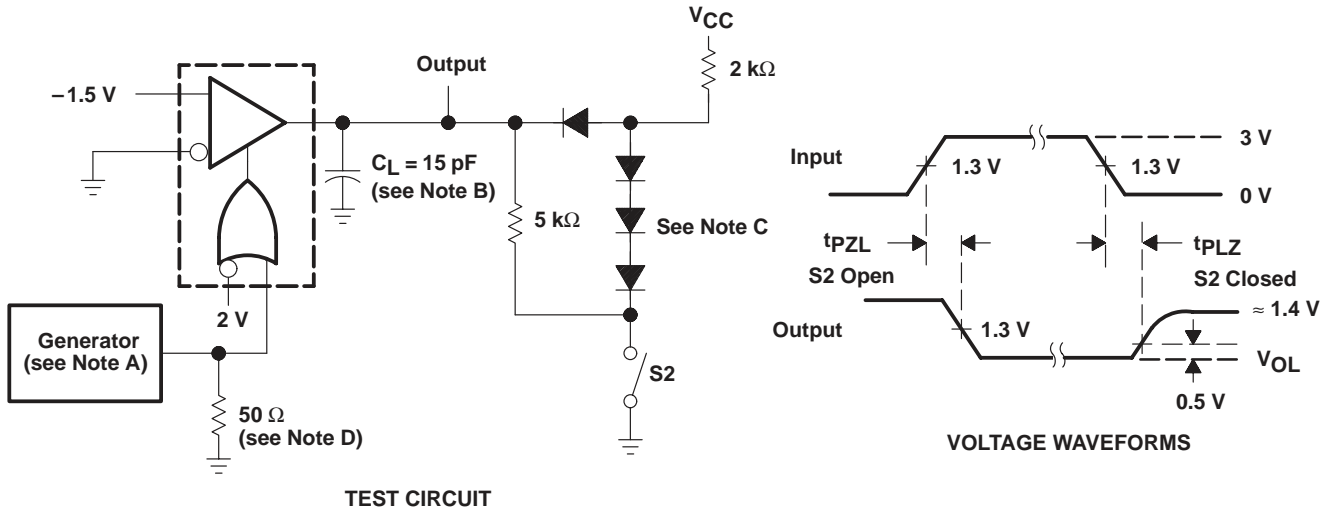
- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle  $\leq$  50%,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.  
 C. All diodes are 1N916 or equivalent.  
 D. To test the active-low enable  $\overline{G}$ , ground G and apply an inverted input waveform to  $\overline{G}$ .

Figure 2.  $t_{pZH}$  and  $t_{pZH}$  Test Circuit and Voltage Waveforms

# SN55LBC173 QUADRUPLE LOW-POWER DIFFERENTIAL RECEIVER

SGLS081A – MARCH 1995 – REVISED JUNE 2000

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle ≤ 50%,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.  
 C. All diodes are 1N916 or equivalent.  
 D. To test the active-low enable  $\overline{G}$ , ground G and apply an inverted input waveform to  $\overline{G}$ .

Figure 3.  $t_{pZL}$  and  $t_{pLZ}$  Test Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS

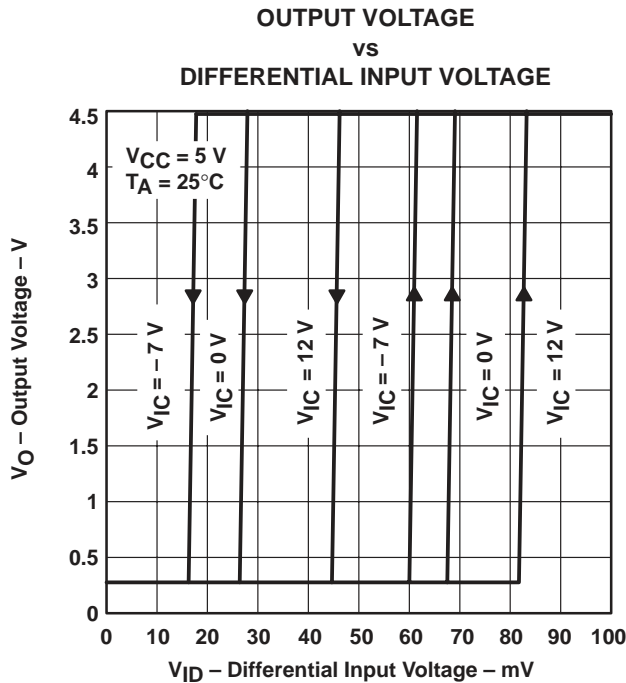


Figure 4

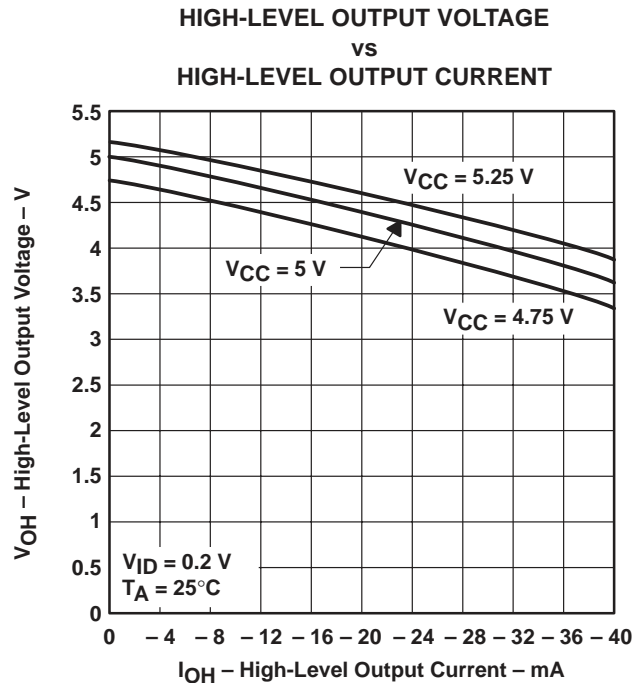


Figure 5

TYPICAL CHARACTERISTICS

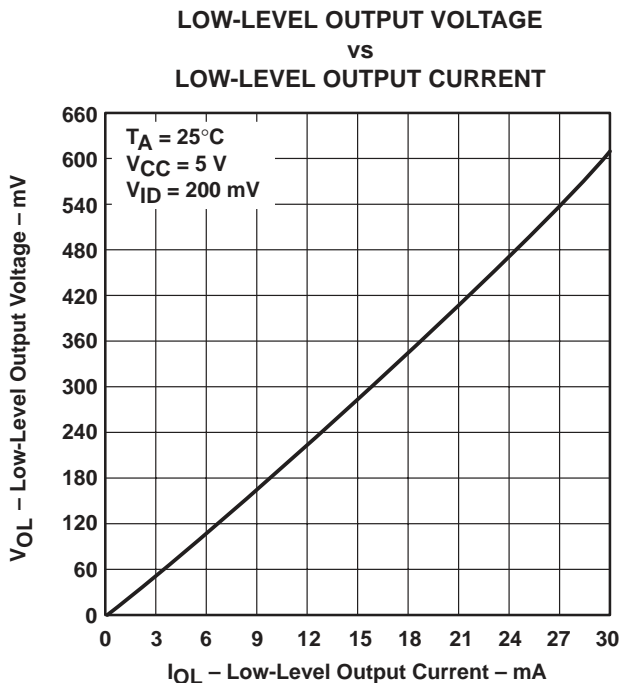


Figure 6

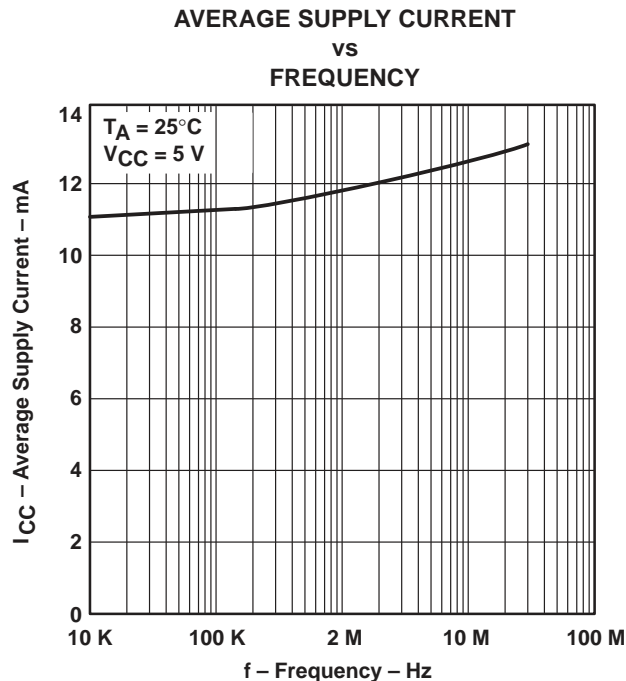


Figure 7

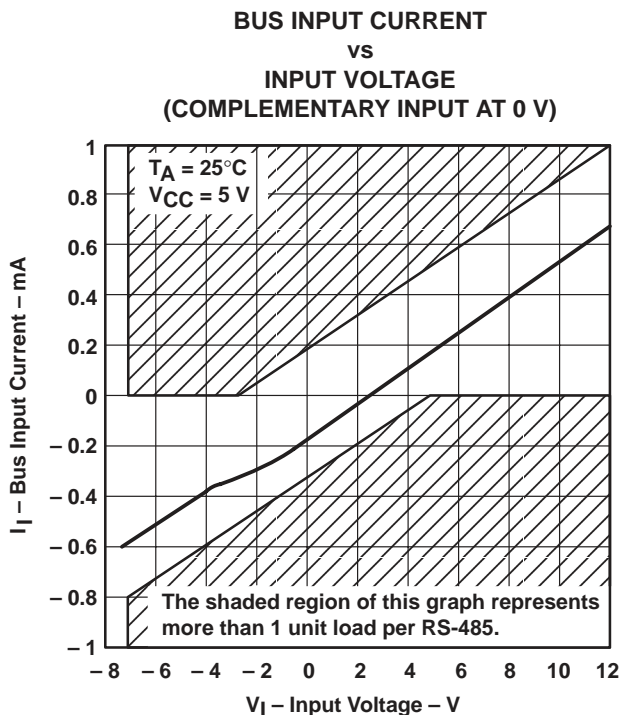


Figure 8

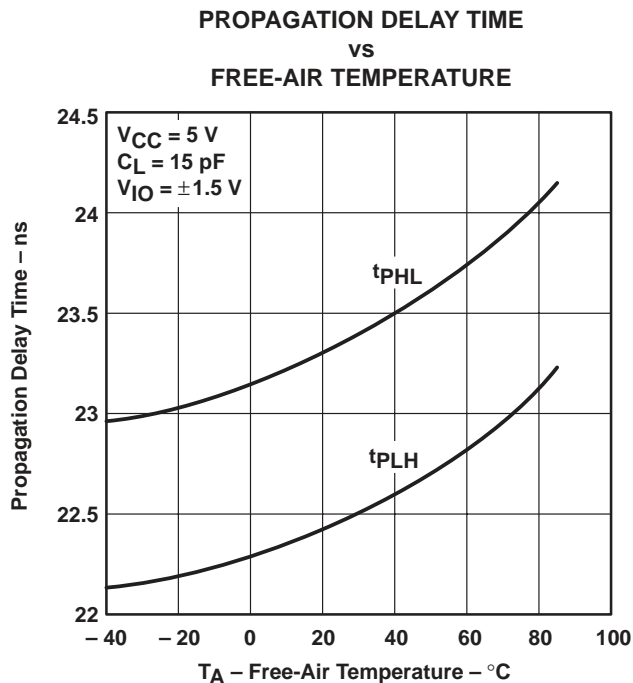


Figure 9

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9076604Q2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9076604Q2A SNJ55 LBC173FK	<a href="#">Samples</a>
5962-9076604QEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QE A SNJ55LBC173J	<a href="#">Samples</a>
5962-9076604QFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QF A SNJ55LBC173W	<a href="#">Samples</a>
SNJ55LBC173FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9076604Q2A SNJ55 LBC173FK	<a href="#">Samples</a>
SNJ55LBC173J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QE A SNJ55LBC173J	<a href="#">Samples</a>
SNJ55LBC173W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QF A SNJ55LBC173W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN55LBC173 :**

- Catalog : [SN75LBC173](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

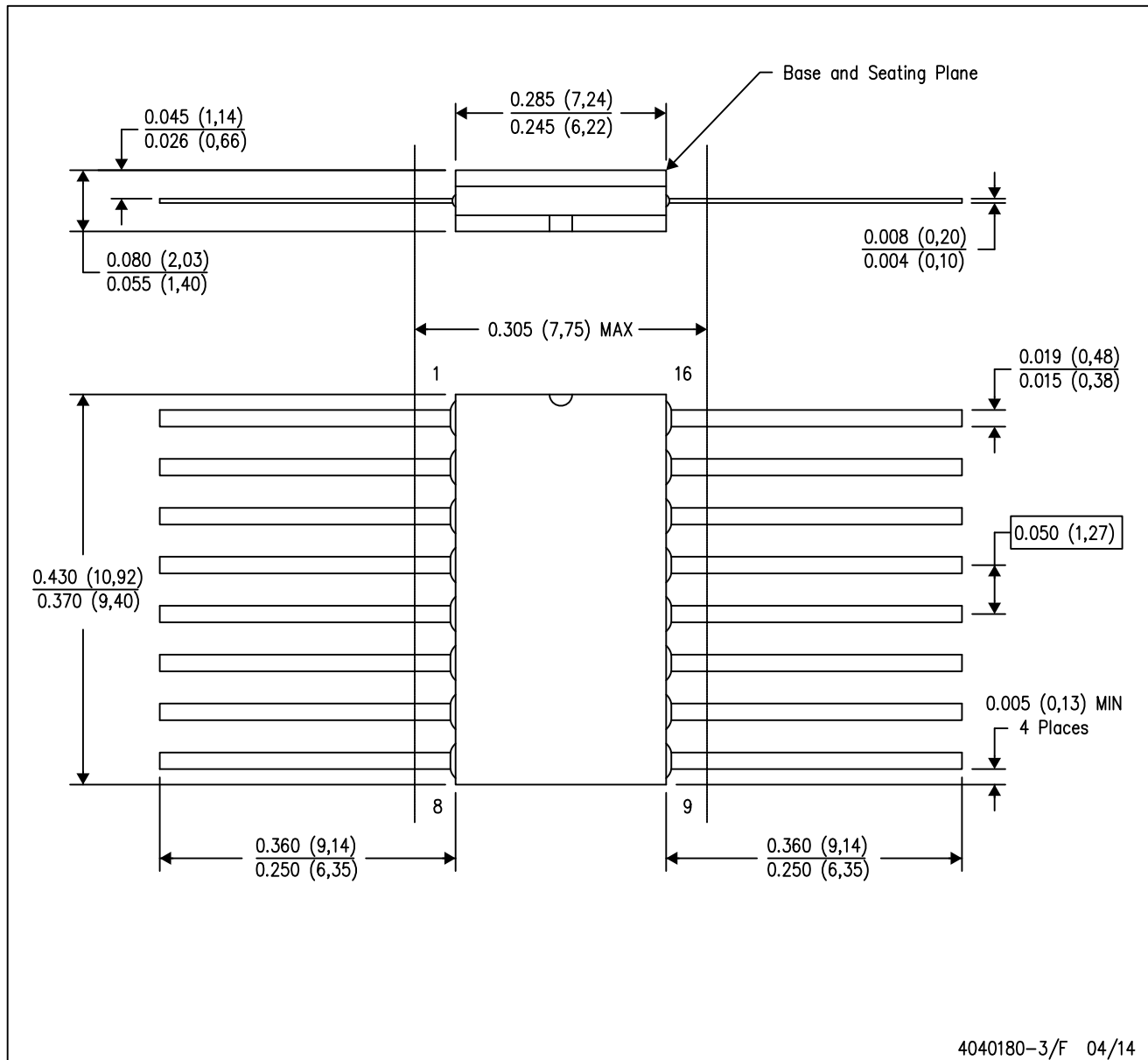
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9076604Q2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9076604QFA	W	CFP	16	1	506.98	26.16	6220	NA
SNJ55LBC173FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ55LBC173W	W	CFP	16	1	506.98	26.16	6220	NA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP2-F16

## GENERIC PACKAGE VIEW

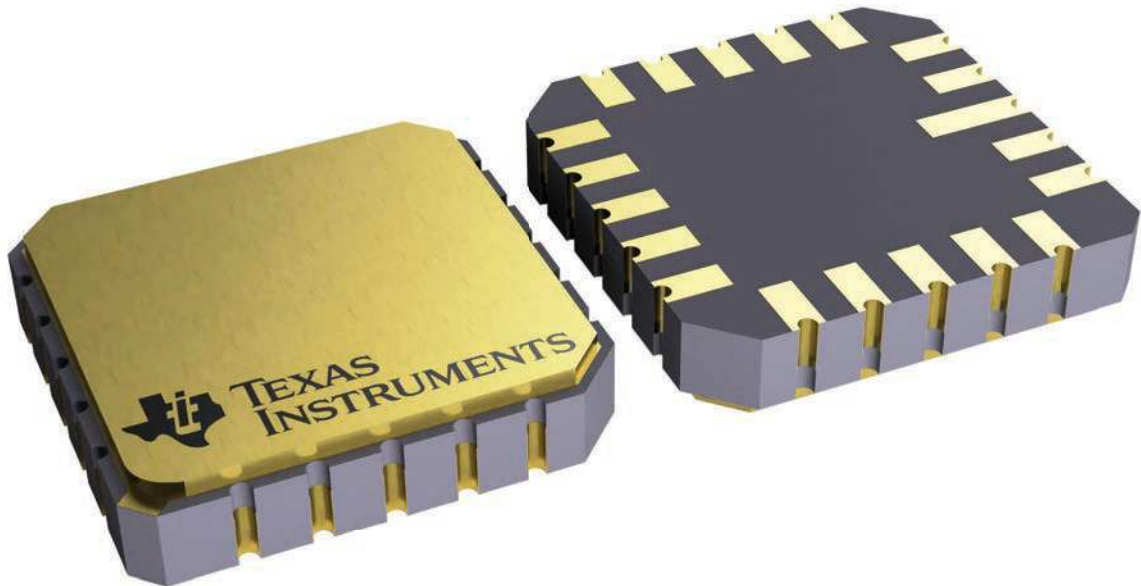
**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2023, Texas Instruments Incorporated